TITLE: SEMICONDUCTOR MATERIAL CUTTING METHOD

ABSTRACT

Proposed is a semiconductor material cutting method capable of more rapidly performing a process of cooling a semiconductor material by using a washing nozzle before a cutting process is performed. Therefore, an environment similar to a cutting water spraying environment during the process of cutting the semiconductor material is formed in the process of cooling the semiconductor material, so that the semiconductor material may be pre-contracted. In addition, in the method, since a position of a scheduled division line of the semiconductor material is aligned while the semiconductor material is in a cooled and contacted state, cutting quality is improved without having a misalignment between the scheduled division line of the semiconductor material and a position of an actual division line.

FIG. 3